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**JPCA**

**IEC/PAS 62326-20**

Edition 1.0 2011-01

# **PUBLICLY AVAILABLE SPECIFICATION**

## **PRE-STANDARD**



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**Printed boards –  
Part 20: Electronic circuit board for high-brightness LEDs**

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

PRICE CODE

**X**

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### PRINTED BOARDS –

### Part 20: Electronic circuit board for high-brightness LEDs

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## PRINTED BOARDS –

### Part 20: Electronic circuit board for high-brightness LEDs

#### 1 Scope

This PAS specifies the properties of the electronic circuit board for high-brightness LEDs (hereafter described as “ECB”).

NOTE Standards relevant to the present standards are given below.

JPCA-TD01 Terms and definitions for printed circuits

JIS C 5603 Terms and definitions for printed circuits

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